TSEV01S01B90

- Contact less Temperature Measurement
- Small Size
- High Accuracy
- Digital Interface Bus (SPI)

DESCRIPTION

The TSEV01S01B90 is a contact-less temperature measuring system for OEM use based on the detection of infrared radiation.

The TSEV01S01B90 is equipped with an infrared sensor (Thermopile) in front. The Thermopile Sensor has to be pointed at the target object.

The basic working principle is:

- Detection of infrared radiation with a Thermopile sensor, which turns incoming radiation to an analogue voltage
- Determination of sensor temperature using a thermistor
- Calculation of ambient and object temperature using a processing unit
- Providing the ambient and objects temperature at digital output bus (SPI)

The TSEV01S01B90 module is suitable for a wide range of application where non-contact temperature measurement and high accuracy are required.

FEATURES

0°C – 100°C Measurement Range
Small Size
Up to 2°C Accuracy
2mA Current Consumption

APPLICATIONS

Contact less Temperature Measurement
Climate Control
Industrial Process Control
Household Applications

TSEV01S01B90

ABSOLUTE MAXIMUM RATINGS

Absolute maximum ratings are limiting values of permitted operation and should never be exceeded under the worst possible conditions either initially or consequently. If exceeded by even the smallest amount, instantaneous catastrophic failure can occur. And even if the device continues to operate satisfactorily, its life may be considerably shortened.

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Supply Voltage	Vccmax	Stabilized supply voltage	-0.2		4.0	V
Operating Temperature	Topmax		-10		85	°C
Storage temperature	Tstor		-40		85	°C
Humidity	HumL	-40°C - +50°C			85	%
Humidity	HumH	+50°C - +85°C			50	%

OPERATING CONDITIONS

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Supply Voltage	Vcc	Stabilized supply voltage	2.6	3.3	3.6	V
Operating Temperature Range	Top		0		85	°C
Emission Coefficient	ε		0.98			

SENSOR CONDITIONS

If not otherwise noted, 3.3V supply voltage and object with ε =0.98 were applied.

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Field of View	FOV	Total field of view at 50% signal level		90		°
Wavelength Range	S			5.0 (cut on)		µm

OPERATIONAL CHARACTERISTICS

If not otherwise noted, 3.3V supply voltage and object with ε =0.98 were applied.

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Object Temperature Range	Tobj		0		100	°C
Resolution	Res				0.02	°C
Supply Current[1]	I	No output load		2		mA
Data Output Rate	Fout			1		Hz
Standard Start-Up Time	tStart				3	s

TOLERANCES

If not otherwise noted, 3.3V supply voltage and object with ε =0.98 were applied.

Parameter	Symbol	Sensor Temp.	Object Temp.	Max	Unit
Accuracy Standard Temp [1]	AccS	$15 < T_{sen} < 35$	$40 < T_{obj} < 80$	2	°C
Accuracy Extended Temp. 1 [2]	AccE1	$T_{sen} < 15, T_{sen} > 35$	$40 < T_{obj} < 80$	3	°C
Accuracy Extended Temp. 2 [2]	AccE2	$15 < T_{sen} < 35$	$T_{obj} < 40, T_{obj} > 80$	3	°C
Accuracy Extended Temp. 3 [2]	AccE3	$T_{sen} < 15, T_{sen} > 35$	$T_{obj} < 40, T_{obj} > 80$	4	°C

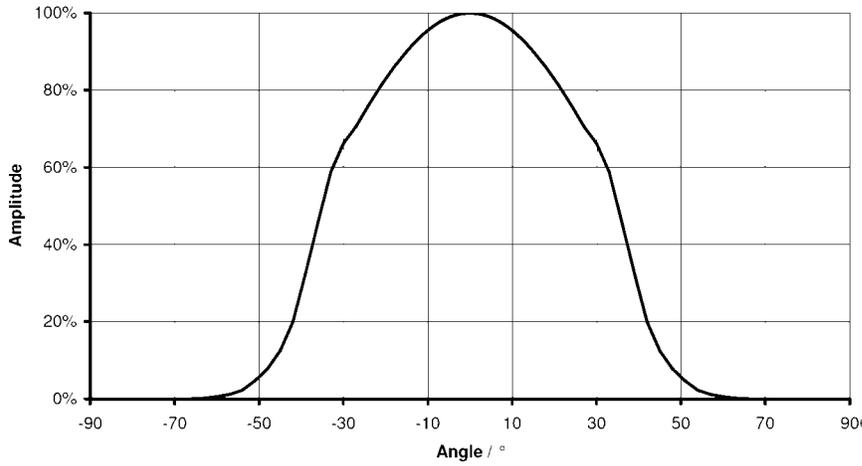**OTHER TEMPERATURE RANGES AND ACCURACIES ARE AVAILABLE ON REQUEST.**

[1] Proved while production
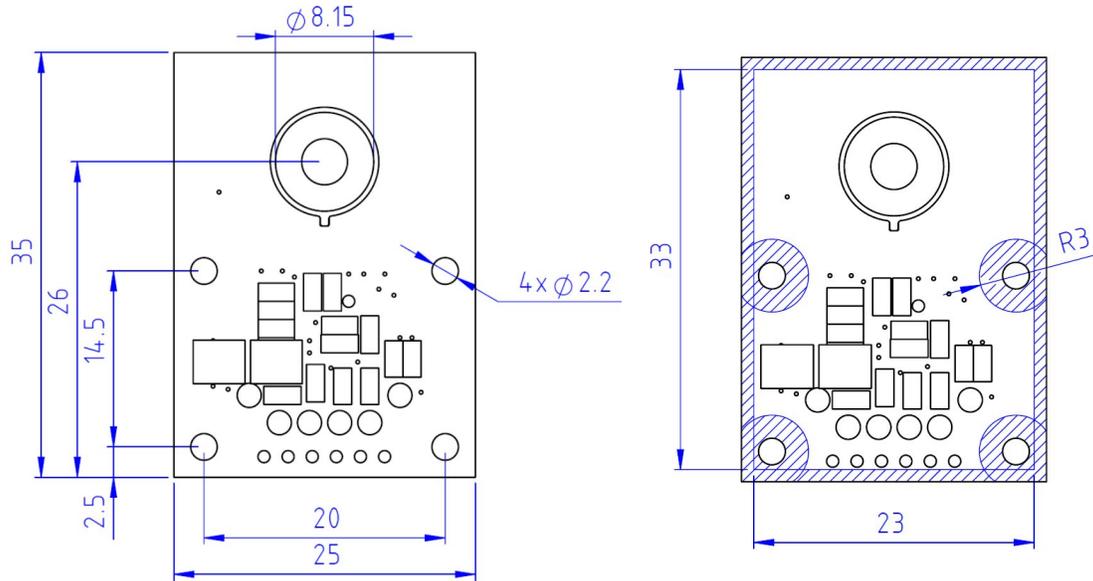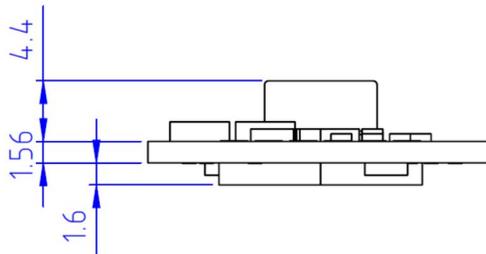[2] Proved by design

TSEV01S01B90

SENSOR FIELD OF VIEW

MECHANICAL DIMENSIONS

4 x ⌀2.2

R3

Only use hatched areas for mechanical assembly (screws, nuts, etc).

TSEV01S01B90

TERMINALS

Connector: solder pads

Pin	Name	Description	Type
1	VDD	Supply Voltage	Supply
2	GND	Ground	Supply
3	SCL	SPI Clock	Interface
4	MISO	SPI Master In / Slave Out	Interface
5	MOSI	SPI Master Out / Slave In	Interface
6	SCE	SPI Chip Enable	Interface

Pin 1   Pin 6

BLOCK DIAGRAM

TSEV01S01B90

INTERFACE

PARAMETER

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Baudrate	FSPI		10		100	kHz
Data Bits				8		
Chip Select				Yes		
Input Voltage Low					0.9	V
Input Voltage High		Vcc = 3.3V	2.1			V
Output Voltage Low		1mA			0.3	V
Output Voltage High		Vcc = 3.3V, 1mA	3.0			V

SIGNAL DESCRIPTION

- SCE (Chip Select)   0 = Enable, 1 = Disable
- CKP   0
- CKE   1
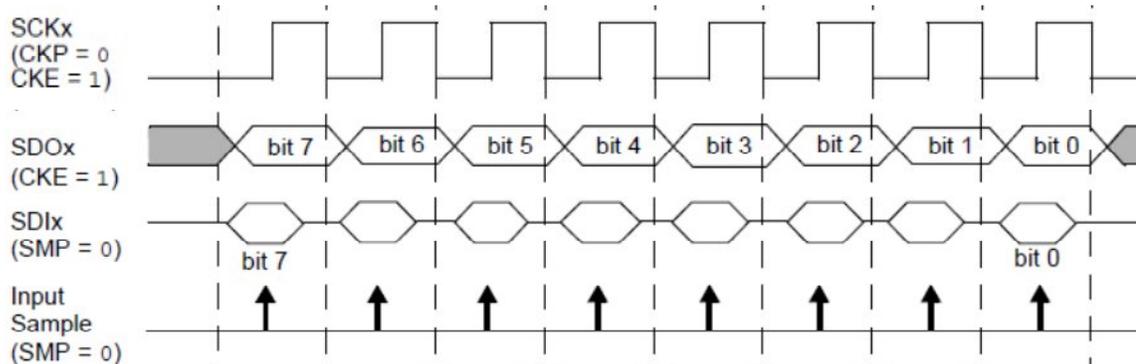
SAMPLE CODE

Sample Code for sending 8 bits and reading 8 bits while sending 8 clocks.

```
// Setting directions
    TRISC4 = 1;   // SDI = Input
    TRISC5 = 0;   // SDO = Output
    TRISC3 = 0;   // SCL = Output
// Reset SPI Lines
    RC5 = 0;      // SDO
    RC3 = 0;      // SCL

    for (c = 0; c < 8; c++)
    {
        cReceive = cReceive << 1;       // Shift Receive Register
        RC3 = 0;                        // SCL = 0
        RC5 = (cTransmit >> (7 - c));   // Outupt next Bit on SDO
        RC3 = 1;                        // SCL = 1
        cReceive = cReceive | RC4;      // Input next Bit on SDI
    }
    RC3 = 0;
    RC5 = 0;
    return cReceive;
```
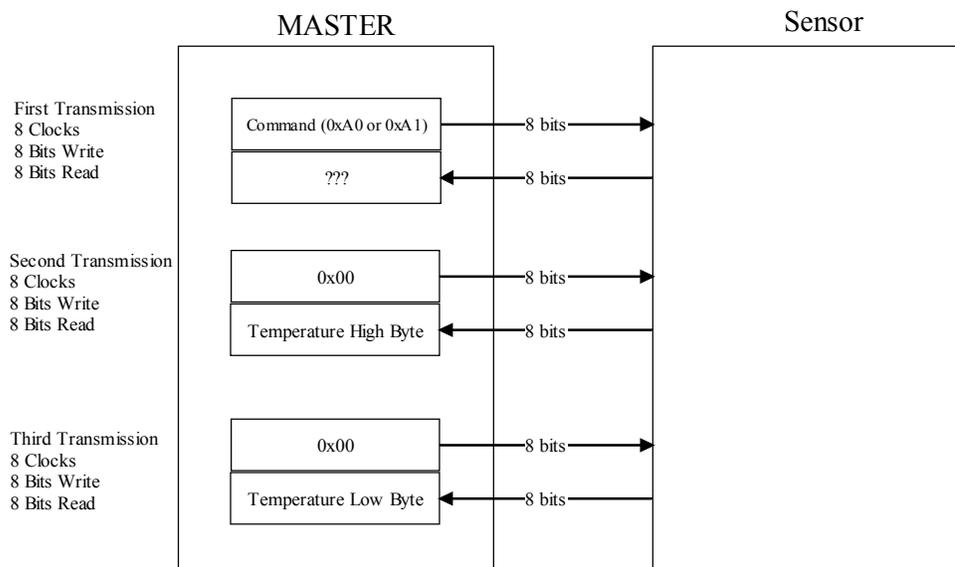
TSEV01S01B90

AMBIENT AND OBJECT TEMPERATUREMEASUREMENT

Please refer following table for SPI commands to read object temperature and ambient temperature. Both values are transmitted in hundredth of degrees.

Com	Description	Reply	Bytes
0xA0	Sensor Temperature	Sensor temperature in hundredth of degrees Celsius	2
0xA1	Object Temperature	Object temperature in hundredth of degrees Celsius	2

SEQUENCE OF TRANSMISSION

Enable SCE (SCE=0) before transmission of "Command". Release SCE (SCE=1) after reading last byte.

EXAMPLE OF TEMPERATURE CALCULATION

For reading object temperature send: 0xA1

Return values i.e.:

Byte(0) = ???   discard reading

Byte(1) = 0x1A   (=26)

Byte(2) = 0xB0   (=176)

Tobj = (256 * Byte(1) + Byte(2)) / 100 = (256 * 26 + 176) / 100 = 68.32°C

NAMING CONVENTION

TSEV01 S 01 B 10

Series —————————————————————————

Interface (S = SPI, I = I^{2}C) ————————————

Variant (01, 02, ...) ————————————————

Option (B = Basic, C = Comfort) ————————

Field of View at 50% Signal Level (5°, 10°, ...) ————
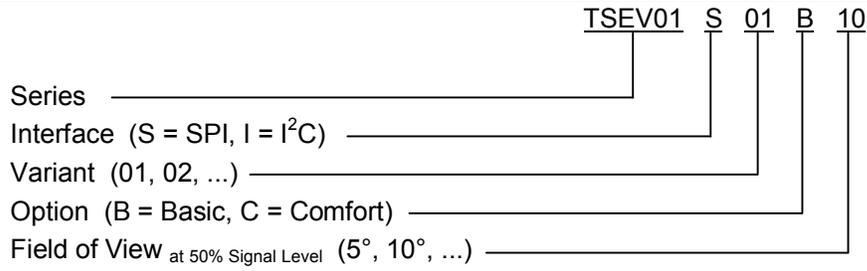
TSEV01S01B90

ORDER INFORMATION

Please order this product using following:

| Part Number | Part Description |
| G-TPMO-020 | TSEV01S01B90 |

EMC

Due to the use of these modules for OEM application no CE declaration is done.

Especially line coupled disturbances like surge, burst, HF etc. cannot be removed by the module due to the small board area and low price feature. There is no protection circuit against reverse polarity or over voltage implemented.

The module will be designed using capacitors for blocking and ground plane areas in order to prevent wireless coupled disturbances as good as possible.

DEFINITIONS AND DISCLAIMERS

- Application information – Applications that are described herein for any of these products are for illustrative purpose only. MEAS Deutschland GmbH makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

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TECHNICAL CONTACT INFORMATION